



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

## PRODUCT CHANGE NOTIFICATION

**PCN:** PCN145354

**Date:** December 19, 2014

**Subject:** Qualification of New Die Attach Epoxy and New Substrate Design for Select 48 Ball Grid Array (BGA) Packages

**To:** PCN ADMIN  
 CYPRESS  
 pcn\_admin@cypress.com

**Change Type:** Minor

**Description of Change:**

Cypress announces the qualification of non-conductive die attach epoxy to replace the conductive die attach epoxy and a substrate design change for select 48 Ball Grid Array (BGA) Packages at Cypress Philippines (CML). This change is to improve the process control resulting in better product quality, field reliability and continuity of supply.

New and Current Bill of Materials:

Material	New Bill of Materials (CML)	Current Bill of Materials (CML )
Mold Compound	Kyocera KE-G2270	Kyocera KE-G2270
Die Attach	Ablestik - 2035SC (Non-conductive epoxy)	Henkel - QMI 506 (conductive epoxy)
Substrate	Kinsus - SUBAB48KPA	Unimicron – SUBAB48KP
Bond Wire	Au, 0.8 mil/CuPd 0.8 mil	Au, 0.8 mil/CuPd 0.8 mil
Lead Finish	Sn/Ag/Cu	Sn/Ag/Cu

**Benefit of Change:**

This change will minimize the package warp and reduces stress on the package while applying heat during reflow process. This in turn provides the means for Cypress to continue to meet our customers' requirements and meet our delivery commitments in dynamic market conditions.

**Part Numbers Affected:** 20

**Affected Parts:** Please refer to the attached affected part list file.

**Qualification Status:**

The new die attach epoxy and the new substrate have been qualified through a series of tests documented in Qualification Test Plan (QTP) 143807. The qualification report can be found as an attachment to this notification or by visiting [www.cypress.com](http://www.cypress.com) and typing the QTP number in the keyword search window.

**Sample Status:**

Qualification samples are not built ahead of time for all part numbers affected by this change. Please review the attached file for a list of affected part numbers with their associated sample ordering part numbers. Please contact your Sales Representative as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

**Approximate Implementation Date:**

Effective 90 days from the date of this notification Cypress will transition to shipments of the affected part numbers with the newly qualified die attach material.

**Anticipated Impact:**

None anticipated. Products manufactured at CML with the new bill of materials are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

**Method of Identification:**

Cypress maintains traceability of product to wafer level, including wafer fabrication and assembly location, through the lot number marked on the package. There will be no changes to the ordering codes or marking on production material shipped after the change implementation date.

**Response Required:**

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at [pcn\\_adm@cypress.com](mailto:pcn_adm@cypress.com).

Sincerely,

Cypress PCN Administration